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CENTRAL FAX CENTER

Practitioner's Docket No. MI22-1839

SEP 02 2004

PATENT

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Farnworth et al, Warren M.

Application No.: 10/004,172

Group No.: 3729

Filed: 10/09/01

Examiner: A.D. Tugbang

For: Methods of Bonding Solder Balls to Bond Pads on a Substrate, and Bonding Frames

Commissioner for Patents  
Washington, D.C. 20231

## CERTIFICATION OF FACSIMILE TRANSMISSION

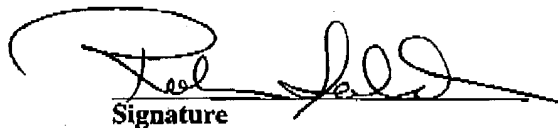
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Examiner Interview Summary of September 2, 2004

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CENTRAL FAX CENTERApplication Serial No. 10/004,172  
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## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No. .... 10/004,172  
Filing Date ..... October 9, 2001  
Inventor ..... Warren M. Farnworth et al.  
Assignee ..... Micron Technology, Inc.  
Group Art Unit ..... 3729  
Examiner ..... A.D. Tugbang  
Attorney's Docket No. .... MI22-1839  
Title: Methods of Bonding Solder Balls to Bond Pads on a Substrate, and Bonding  
Frames

EXAMINER INTERVIEW SUMMARY OF SEPTEMBER 2, 2004

10.

Commissioner for Patents

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Applicant's representative held an interview with Examiner Tugbang on September 2, 2004. Applicant's representative would like to thank Examiner Tugbang for his time and attention to this matter.

Agreement was reached. The Examiner requested minor amendments to the claims to put the case in form for allowance. The following amendments were discussed and agreed upon to claims 7, 11 and 12:

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7. (Currently amended) The method of bonding solder balls of claim 12, wherein said exposing comprises laser bonding the balls with ~~their associated~~ the individual bond pads by fixing the position of the frame and moving a laser beam relative to the frame from ball-to-ball.

11. (Currently amended) The method of bonding solder balls of claim 12, wherein:

said placing comprises placing individual solder balls within individual holes within the frame; and

said exposing of the balls comprises reflowing the solder balls while the balls are within their individual holes, and further comprising after said reflowing, removing the frame from around the reflowed balls.

12. (Currently amended) A method of bonding solder balls to bond pads on a substrate comprising:

placing at least portions of a plurality of solder balls within a frame and in registered alignment with individual bond pads over a substrate by dipping the substrate into a volume of solder balls; and

while the solder ball portions are within the frame, exposing the solder balls to bonding conditions effective to bond the solder balls with respective ones

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of the individual bond pads, wherein said placing comprises placing said ball portions on fluxless bond pad surfaces.

The Examiner stated that he would make the amendments by an Examiner's Amendment and that he would positively state that these amendments do not change the scope of the claims.

Applicant would like to again thank Examiner Tugbang for his time and attention to this matter.

Respectfully submitted,

Dated: 9-2-04

By: 

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Reg. No. 40,045